

Using CC1190 Front End With CC13xx Under FCC 15.247

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ABSTRACT

The CC1190 device is a range extender for 850- to 950-MHz RF transceivers, transmitters, and wireless MCUs from Texas Instruments™. The device increases the link budget by providing a power amplifier (PA) for increased output power, and a low-noise amplifier (LNA) with low noise figure for improved receiver sensitivity, in addition to switches and RF matching for simple design of high-performance wireless systems.

This application note outlines the expected performance when using the CC1310-CC1190 LaunchPad™ Development Kit design under FCC 15.247 in the 902- to 928-MHz frequency band. This application note assumes that the reader is familiar with CC1310 and FCC 15.247 regulatory limits. For details, see [\[1\]](#) and [\[2\]](#).

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1 Abbreviations

Table 1 lists abbreviations used throughout this document.

Table 1. Abbreviations

Abbreviation	Full Term
BER	Bit Error Rate
HGM	High Gain Mode
LP	LaunchPad
PCB	Printed-Circuit Board
PER	Packet Error Rate
RF	Radio Frequency
RSSI	Receive Signal Strength Indicator
RX	Receive, Receive Mode
TX	Transmit, Transmit Mode

2 Electrical Specifications

NOTE: The characteristics in this section are valid only when using the CC1310-CC1190 LaunchPad reference design version 1.1.1 (US version, see [3]) with a 50-Ω load and settings recommended by the SmartRF™ Studio software.

All measurements are done with the following conditions if nothing else is stated:

- $T_C = 25^\circ\text{C}$
- $V_{DD} = 3.3\text{ V}$
- $f = 915\text{ MHz}$

2.1 Operating Conditions

Table 2. Operating Conditions

Parameter	Minimum	Maximum	Unit
Operating frequency ⁽¹⁾	902	928	MHz
Operating supply voltage	2.0	3.6	V
Operating temperature	-40	85	°C

⁽¹⁾ The FCC 915-MHz band.

2.2 Current Consumption

The current is measured for the radio part of the board only. The jumpers to the XDS110 part are removed.

Table 3. Current Consumption

Parameter	Condition	Typical	Unit
Receive current, HGM ⁽¹⁾	50 kbps, 2GFSK, ±25-kHz deviation	11.0	mA
Transmit current	txPower = 0x00CE (26 dBm)	379	mA
	txPower = 0x00C9 (25 dBm)	338	
	txPower = 0x00C6 (24 dBm)	291	
	txPower = 0x00C5 (23 dBm)	269	
	txPower = 0x00C4 (22 dBm)	240	
	txPower = 0x00C3 (20 dBm)	204	
	txPower = 0x00C2 (18 dBm)	158	
	txPower = 0x00C1 (14 dbm)	112	
	txPower = 0x00C0 (7 dBm)	75	

⁽¹⁾ Input signal at -100 dBm. $V_{DD} = 3.6$ V.

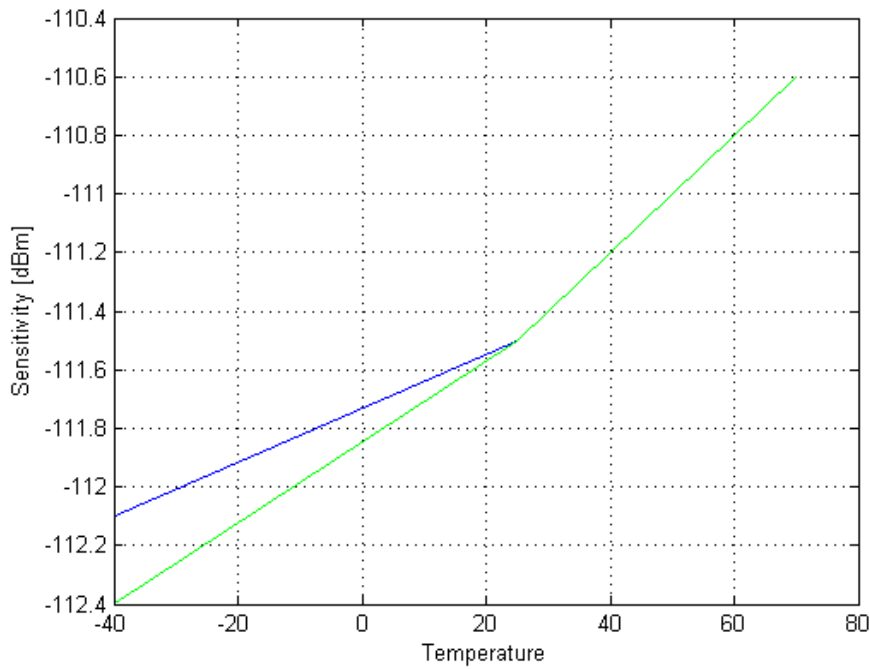
2.3 Receive Parameters

Table 4. Receive Parameters

Parameter	Condition	Typical	Unit
Sensitivity ⁽¹⁾ , HGM	50 kbps 2-GFSK	-111.5	dBm
	SimpleLink™ LRM 5 kbps	-120.8	dBm
Saturation, HGM	Maximum input power level for 1% BER	+10	dBm
Selectivity and blocking, HGM	±1 MHz from wanted signal	47	dB
	±2 MHz from wanted signal	59	
	±5 MHz from wanted signal	66	
	±10 MHz from wanted signal	74	

⁽¹⁾ Sensitivity limit is defined as 1% bit error rate (BER). Packet length is 3 bytes.

2.3.1 Typical RX Performance vs Temperature and VDD



- (1) Blue is $V_{DD} = 3.3\text{ V}$
- (2) Green is $V_{DD} = 3.6\text{ V}$

Figure 1. Typical Sensitivity vs Temperature, HGM, 50 kbps

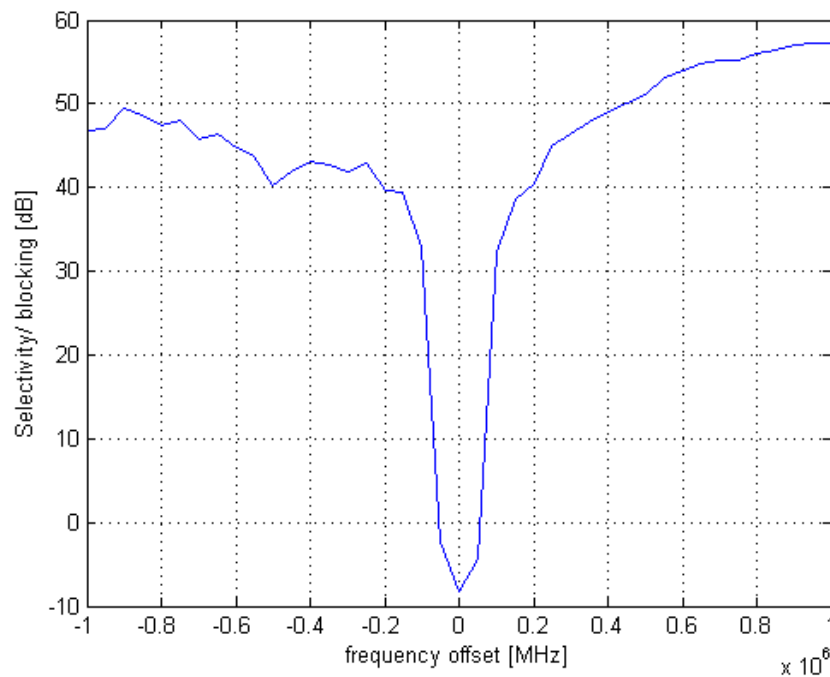


Figure 2. Typical Selectivity

2.3.2 Receive Signal Strength Indicator (RSSI)

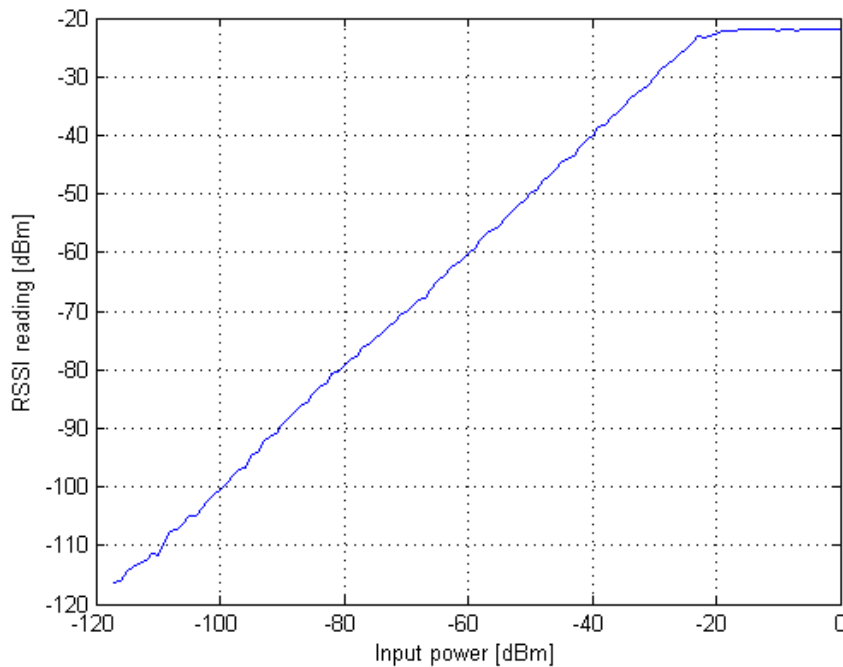


Figure 3. Typical RSSI vs Input Level, HGM, 50 kbps

PER versus level was run, and the reported RSSI was compared with the signal generator level. The RSSI level saturates when the input power level is above -24 dBm. To get the correct RSSI offset, the following override must be modified:

Change 0x00FB88A3 to 0x000388A3.

2.4 Transmit Parameters

The output power variation as a function of temperature will be a combination of the CC1310 output power variation and the CC1190 output power variation. Because the CC1190 device operates in saturation, the CC1190 variation will have the largest contribution. For this reason, the temperature compensation of the CC1310 output power is turned off.

Due to the current consumption and long power cables, the test system has a given IR drop from the power supply to the DUT. The voltage on the supply was therefore increased some to give the stated voltage on the power pins on the LaunchPad for 25-dBm output power (see [Table 5](#) for the power amplifier values).

Table 5. PA Table

Parameter	Condition	Typical	Unit
Output power, HGM	txPower = 0x00CE	26	dBm
	txPower = 0x00C9	25	
	txPower = 0x00C6	24	
	txPower = 0x00C5	23	
	txPower = 0x00C4	22	
	txPower = 0x00C3	20	
	txPower = 0x00C2	18	
	txPower = 0x00C1	14	
	txPower = 0x00C0	7	

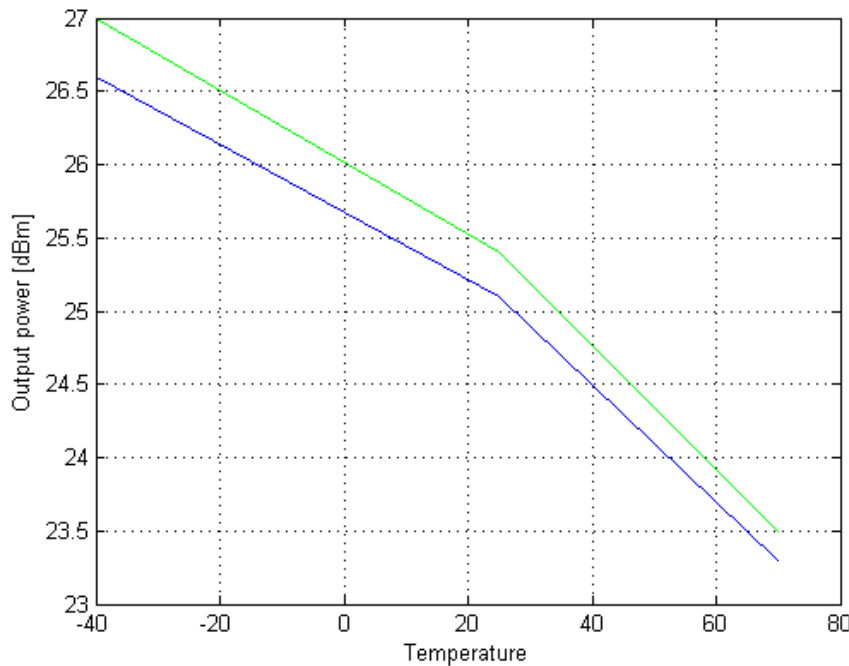
Table 6 lists the spurious emission values.

Table 6. Spurious Emission

Parameter	Condition	Typical	Unit
Spurious emission with txPower = 0x00C9 , HGM	Conducted below 1 GHz	-58	dBm
	Conducted above 1 GHz	-55	
	Conducted second harmonic	-8	
	Conducted third harmonic	-55	
	Radiated second harmonic	-4	
	Radiated third harmonic	-46	

2.4.1 Typical TX Performance vs Temperature and V_{DD}

Figure 4 shows the output power versus temperature for txPower = 0x00C9.



- (1) Blue is $V_{DD} = 3.3$ V
- (2) Green is $V_{DD} = 3.6$ V.

Figure 4. Output Power vs Temperature, txPower = 0xC9

2.4.2 Typical TX Parameters vs Load Impedance

The load impedance presented to the CC1190 PA output is critical to the TX performance of the reference design. The load impedance is selected as a compromise between several criteria, such as output power, efficiency, and the level of the harmonics. The matching components between the PA output and the antenna should transform the 50-Ω antenna impedance to the selected impedance (which the CC1190 PA should detect). This is taken care of by the reference design (see [3]) and a well-matched antenna should be used to get the required performance.

2.5 Duty Cycling

FCC Section 15.209 gives the general limits for the emission of intentional or unintentional radiators. Above 960 MHz, the limit is -41.2 dBm (500 μ V/m at a distance of 3 m). When operating under Section 15.247, the spurious emission must be 20 dB below the carrier unless it falls within one of the restricted bands defined in Section 15.205. When operating in the frequency range of 902 MHz to 928 MHz, the third, fourth, fifth, and sixth harmonics fall within restricted bands. In the restricted bands, the general limits of -41.2 dBm apply.

Pulsed transmissions allow higher peak harmonic and spurious emissions above 1 GHz because an averaging detector is required in the measurements. The average limit must be below -41.2 dBm, but the maximum peak spurious level for pulsed transmission is 20 dB above the average limit. If the duty cycle factor of the periodic signal is known, measuring the peak value and adding a duty cycle relaxation factor determines the average value. The relaxation factor applies to the TX on-time as measured over a 100-ms period. The relaxation factor is $20 \log(\text{TX on-time} / 100 \text{ ms})$ [dB].

As an example, a 50% duty cycle allows for a 6-dB higher peak emission than without duty cycling. Figure 5 shows the relaxation factor for different transmission on-times over a 100-ms period.

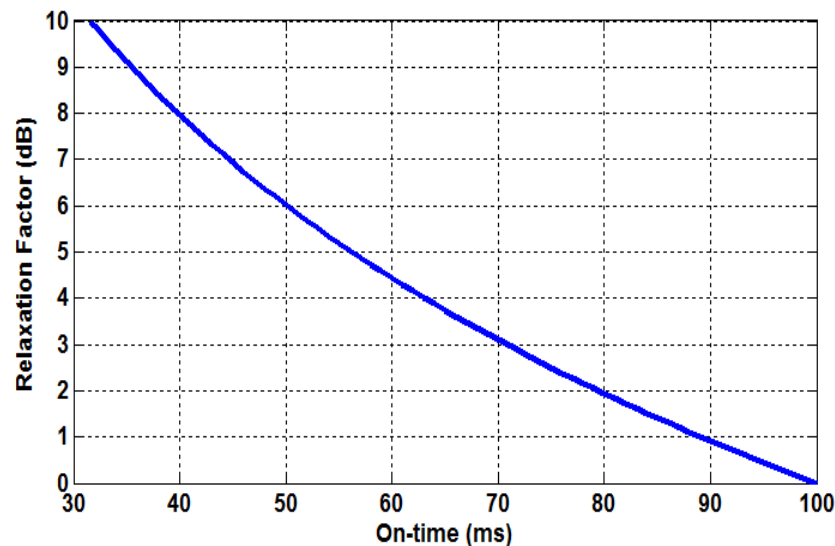


Figure 5. Relaxation Factor vs Duty Cycling

2.6 Measurement Equipment

The measurement equipment used is as follows:

- Spectrum analyzer: Rohde and Schwarz® FSU
- Signal generator: SMIQ 03B

3 Controlling the CC1190

Three digital control pins (PA_EN, LNA_EN, and HGM) set the CC1190 mode of operation. See [Table 7](#).

Table 7. CC1190 Control Logic

PA_EN	LNA_EN	HGM	Mode of Operation
0	0	X	Power Down
0	1	0	RX LGM
0	1	1	RX HGM
1	0	0	TX LGM
1	0	1	TX HGM

On the CC1310-CC1190 LaunchPad, the control signals are mapped to DIOs as follows:

- DIO28 – HGM
- DIO29 – LNA_EN
- DIO30 – PA_EN

HGM should be tied high or low using the pin driver. LNA_EN should be tied to RFC_GPO0 (portID 0x2F) and PA_EN should be tied to RFC_GPO1 (portID 0x30) as described in the *Control External LNA/PA (Range Extender) With I/Os* section in the CC1310 technical reference manual, [CC13x0](#), [CC26x0 SimpleLink™ Wireless MCU](#).

Set the I/Os with the following code:

```
#include <ti/drivers/pin/PINCC26XX.h>
•
•
// LNA
PINCC26XX_setMux(<Handle>, <DIO_LNA>, PINCC26XX_MUX_RFC_GPO0);

// PA
PINCC26XX_setMux(<Handle>, <DIO_PA>, PINCC26XX_MUX_RFC_GPO1);
```

Where <Handle> is the handle returned by PIN_open() and <DIO_LNA> and <DIO_PA> are the pins used to control the LNA_EN and the PA_EN, respectively, on the CC1190.

See the Packet Error Rate example as an example how to control CC1190 from CC1310.

4 SmartRF™ Software Studio

The CC1310-CC1190 LaunchPad can be configured using the SmartRF Studio 7 software.

Version 2.4.2 of SmartRF Studio does not have direct support for CC1310-CC1190. To set the CC1190 control signals click on the *Configure Target* button and set the DIOs as shown in Figure 6. In addition, the frequency must be set to 915 MHz and the correct txPower must be written in the CMD_PROP_RADIO_DIV_SETUP command.

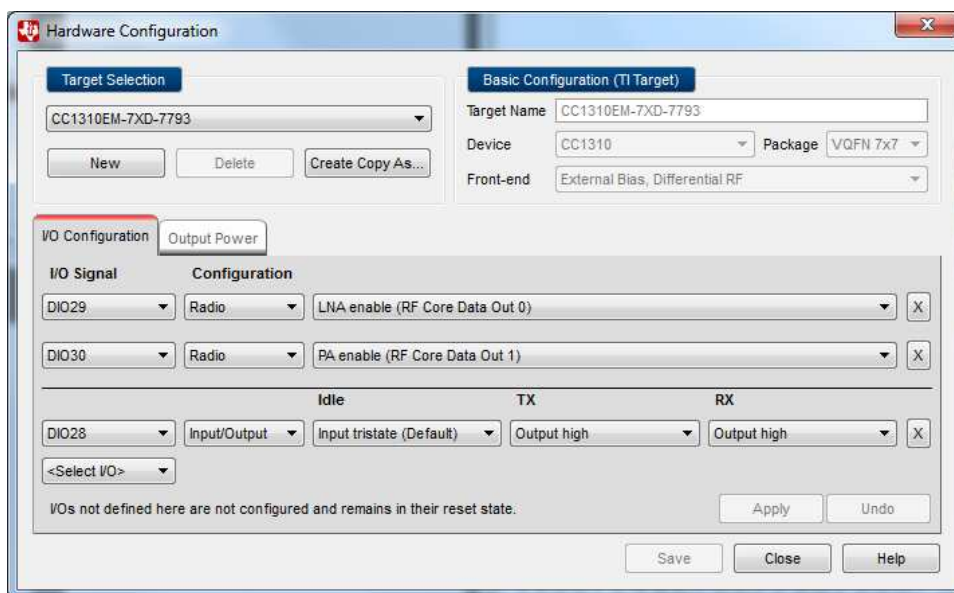


Figure 6. Hardware Configuration

5 Reference Design With Integrated Passive Component (IPC)

The CC1310-CC1190 LaunchPad reference design version 1.1.1 (US) [3] includes schematics and Gerber files. TI highly recommends following the reference design for optimum performance. The reference design also includes a bill of materials (BOM) with manufacturers and part numbers.

5.1 Power Decoupling

Proper power supply decoupling must be used for optimum performance. Capacitors C26, C27, and C30 ensure good RF ground after L21 and thus prevent RF leakage into the power supply lines causing oscillations. The power supply filtering consisting of C216, C217, and L163 ensure well-defined impedance looking toward the power supply.

5.2 I/O Matching and Filtering

The PA and the LNA of the CC1190 are single-ended I/O. A balun is required to transform the differential impedance required by the RF_P/N pins to a single-ended 50- Ω interface. The values of the matching components between the SAW filter and the CC1190 PA input are chosen to present optimum source impedance to the CC1190 PA input with respect to stability.

If a SAW filter is not needed in both RX and TX, the RX and TX path can be split between CC1310 and CC1190.

The CC1190 PA performance is highly dependent on the impedance presented at the output, and the LNA performance is highly dependent on the impedance presented at the input. The impedance is defined by L21 and all components toward the antenna. These components also ensure the required filtering of harmonics to pass regulatory requirements.

The layout and component values must be copied exactly to obtain the same performance as presented in this application note.

5.3 Bias Resistor

R141 is a bias resistor. The bias resistor is used to set an accurate bias current for internal use in the CC1190.

5.4 SAW Filter

A SAW filter is recommended for the CC1310-CC1190 design to attenuate spurs below the carrier frequency that will otherwise violate spurious emission limits under FCC section 15.205 and 15.209. The SAW filter is matched to the CC1190 PA input/LNA output impedance using a series inductor and a shunt capacitor.

A footprint for a 0603 component is placed below the SAW filter to enable testing without the SAW filter.

5.5 PCB Layout Considerations

The TI reference design uses a 1.6-mm (0.062") 4-layer PCB solution.

NOTE: The different layers have different thickness. TI recommends following the recommendation given in the CC1310-CC1190 LaunchPad reference design (US version, see [3]) to ensure optimum performance.

The top layer (layer 1) is used for components and signal routing, and the open areas are filled with metallization connected to ground using several vias. The areas under the two chips are used for grounding and must be well connected to the ground plane with multiple vias. Footprint recommendation for the CC1190 is given in the CC1190 data sheet (see [4]).

Layer 2 is a complete ground plane and is not used for routing. This is done to ensure short return current paths. The low impedance of the ground plane prevents any unwanted signal coupling between any nodes that are decoupled to it.

Layer 3 is a power plane. The power plane ensures low-impedance traces at radio frequencies and prevents unwanted radiation from power traces. Two different power planes are used for CC1310 and CC1190; the power planes are surrounded by ground to reduce unwanted radiation from the board.

Layer 4 is used for routing and ground.

5.6 Shield

TI recommends placing a shield over the CC1190 part of the design to attenuate the radiated third harmonic.

5.7 Attenuation

The CC1310 PA table has few settings that give lower output power than 5 dBm. If larger dynamic range of output levels is needed, attenuation between the CC1310 and CC1190 can be added.

Attenuation could be achieved by a resistive pi attenuator formed by R154, R155, and R156. The attenuator must be designed as 50-Ω in, 50-Ω out. The sensitivity will be a function of the value of the shunt resistors. If R155 and R156 are mounted, C218 and C219 should be 47 pF.

If attenuation is not needed R154, R155, R156, C218, and C219 can be removed and L111 can be connected directly to pin 10 (LNA_OUT) and pin 11 (PA_IN) on CC1190.

5.8 Antenna

The antenna used is described in DN024 (see [11]). Placeholders for a pi filter are included for antenna matching purposes.

6 Reference Design Discrete Components

The CC1310-CC1190 LaunchPad uses the IPC due to space restrictions. The first version of the LaunchPad used discrete components for the balun on CC1310.

The following sections list the measurement results measured for this version of the LaunchPad. The results are average over five LaunchPads. The schematics for the CC1310 and CC1190 part of this version are shown in [Appendix A](#).

6.1 Current Consumption

Table 8. Current Consumption

Parameter	Condition	Typical	Unit
Receive current, HGM ⁽¹⁾	50 kbps, 2GFSK, ±25-kHz deviation	11.3	mA
Transmit current	txPower = C7	511	mA
	txPower = C6	424	
	txPower = C5	386	
	txPower = C4	362	
	txPower = C3	331	
	txPower = C2	284	
	txPower = C1	213	
	txPower = C0	118	

⁽¹⁾ Input signal at -100 dBm

6.2 Receive Parameters

Table 9. Receive Parameters

Parameter	Condition	Typical	Unit
Sensitivity ⁽¹⁾ , HGM		-111.9	dBm
Saturation, HGM	Maximum input power level for 1% BER	10	dBm
Selectivity and blocking, HGM	±200 kHz from wanted signal	38	dB
	±1 MHz from wanted signal	45	
	±2 MHz from wanted signal	58	
	±5 MHz from wanted signal	64	
	±10 MHz from wanted signal	73	

⁽¹⁾ Sensitivity limit is defined as 1% BER. Packet length is 3 bytes.

PER versus level was run, and the reported RSSI was compared with the signal generator level. The RSSI level saturates when the input power level is above -24 dBm. To get the correct RSSI offset, the following override must be modified:

Change 0x00FB88A3 to 0x000388A3.

When doing a code export from SmartRF Studio, this override is part of the pOverrides[] structure.

6.3 Transmit Parameters

The output power variation as a function of temperature will be a combination of the CC1310 output power variation and the CC1190 output power variation. Because the CC1190 device operates in saturation, the CC1190 variation will have the largest contribution. For this reason, the temperature compensation of the CC1310 output power is turned off.

At the time of measurement, high-quality cables fitting the JSC connector were not available, so semirigid cables were used. These semirigid cables typically have a loss equal to 0.2 to 0.25 dB, which is not accounted for in [Table 10](#).

A CC1190 device was moved from a CC1310-CC1190 LaunchPad version 1.0.1 to a CC1310-CC1190 LaunchPad version 1.1.1 and the output power was increased by 1 dB (from 26 dBm to 27 dBm) with all other settings equal. This indicates that the 1.0.1 version of the LP was populated with a production batch of CC1190 that gives higher output power than the production batch that was used on the 1.1.1 version of the board.

Table 10. PA Table

Parameter	Condition	Typical	Unit
Output power, HGM	txPower = 0x00C7	26.1	dBm
	txPower = 0x00C6	26.7	dBm
	txPower = 0x00C5	26.3	dBm
	txPower = 0x00C4	25.8	dBm
	txPower = 0x00C3	25.0	dBm
	txPower = 0x00C2	23.6	dBm
	txPower = 0x00C1	20.8	dBm
	txPower = 0x00C0	14.1	dBm

[Table 11](#) lists the spurious emission values.

Table 11. Spurious Emission

Parameter	Condition	Typical	Unit
Spurious emission with txPower = 0x00C4, HGM	Conducted below 1 GHz	not measured	dBm
	Conducted above 1 GHz	not measured	dBm
	Conducted second harmonic	-20	dBm
	Conducted third harmonic	-51	dBm
	Radiated second harmonic	not measured	dBm
	Radiated third harmonic	not measured	dBm

7 Disclaimer

The CC1310-CC1190 Launchpad is intended for use for ENGINEERING DEVELOPMENT, DEMONSTRATION, OR EVALUATION PURPOSES ONLY and is not considered by TI to be a finished end-product fit for general consumer use. Persons handling the products must have electronics training and observe good engineering practice standards. As such, the goods being provided are not intended to be complete in terms of required design-, marketing-, and/or manufacturing-related protective considerations, including product safety and environmental measures typically found in end products that incorporate such semiconductor components or circuit boards. It is the end user's responsibility to ensure that his system complies with applicable regulations.

8 References

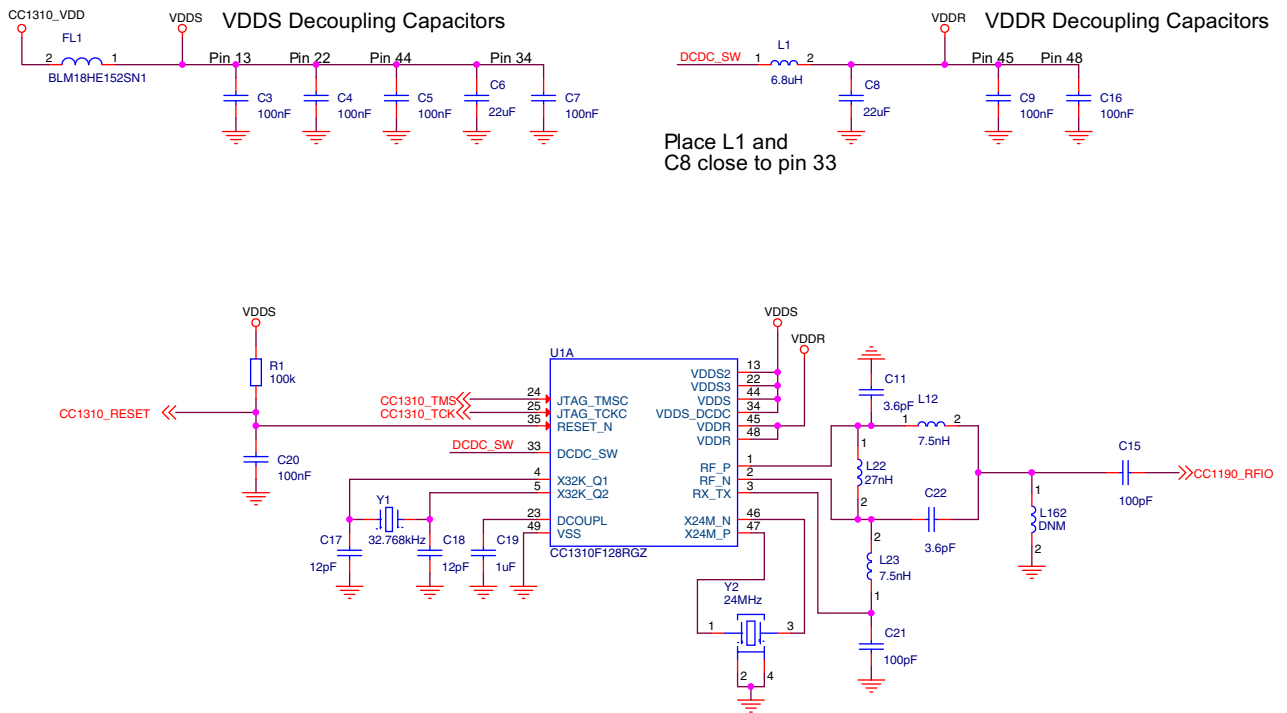
The references for this document follow:

1. [CC1310 SimpleLink™ Ultra-Low-Power Sub-1 GHz Wireless MCU data sheet](#)
2. IEEE 15.247, see the [Electronic Code of Federal Regulations](#) website
3. [CC1310-CC1190 reference design US](#)
4. Texas Instruments™ CC1190 Data Sheet [850-MHz to 950-MHz RF Front End](#)
5. [Final draft ETSI EN 300 220-1 V2.4.1 \(2012-01\)](#)
6. [ERC Recommendation 70-03](#)
7. [SmartRF Studio](#)
8. [CC-Antenna-DK2 and Antenna Measurements Summary application report](#)
9. [DNO24—Monopole PCB Antenna with Single or Dual Band Option design note](#)

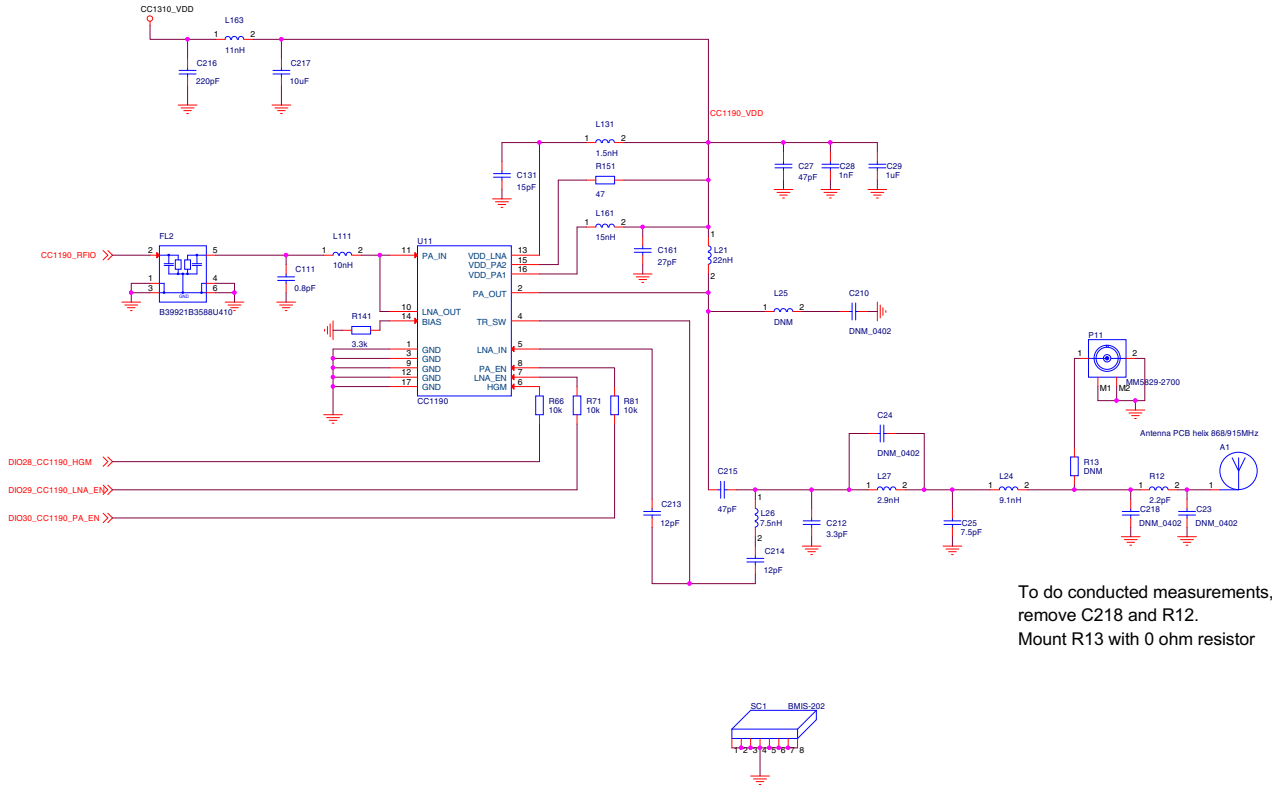
Schematics

A.1 Schematics

CC1310 RF



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